

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

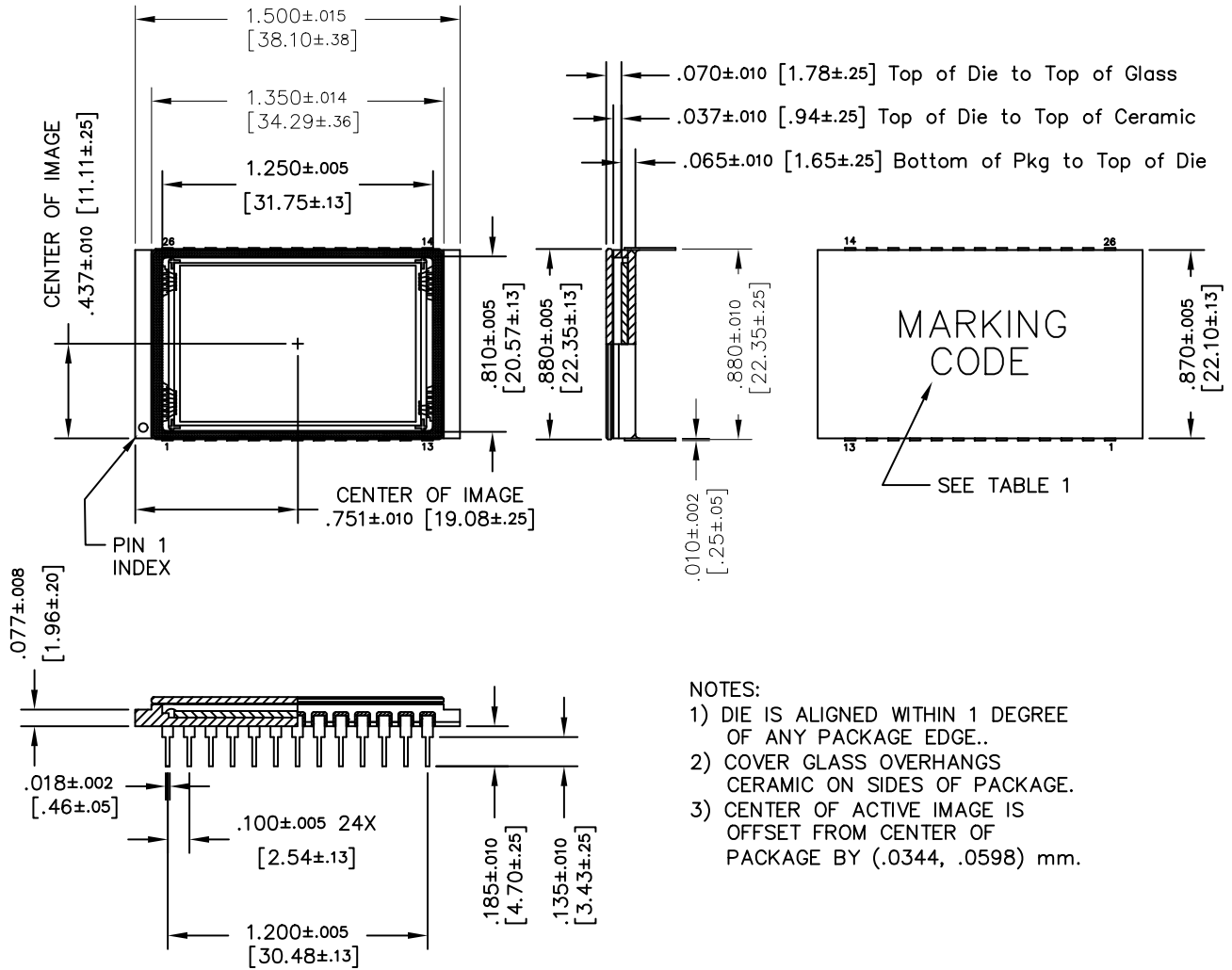
ON Semiconductor®



CERAMIC DIP 26, 38.1x22.61, 2.54P

CASE 125BA
ISSUE O

DATE 30 JUN 2014



NOTES:

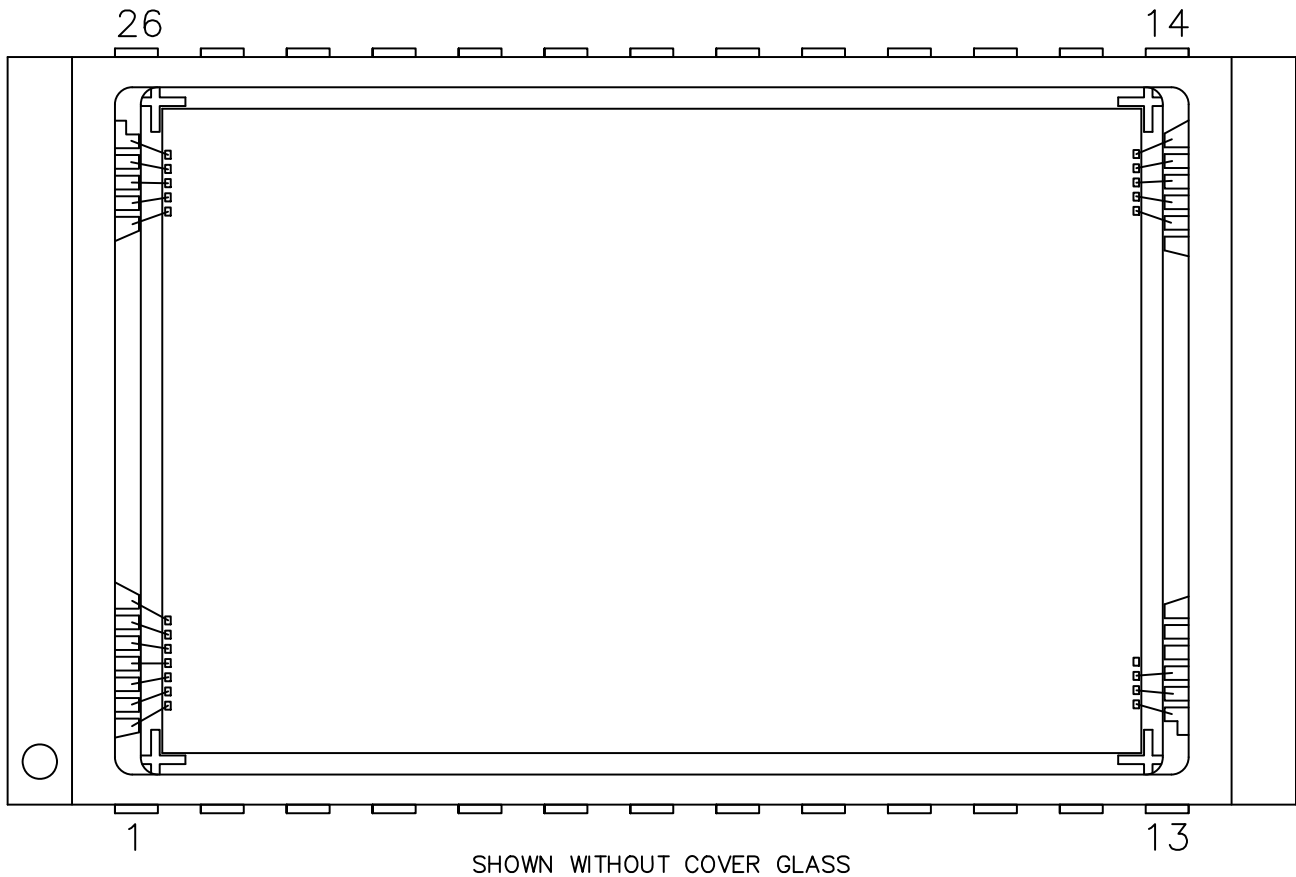
- 1) DIE IS ALIGNED WITHIN 1 DEGREE OF ANY PACKAGE EDGE..
- 2) COVER GLASS OVERHANGS CERAMIC ON SIDES OF PACKAGE.
- 3) CENTER OF ACTIVE IMAGE IS OFFSET FROM CENTER OF PACKAGE BY (.0344, .0598) mm.

DOCUMENT NUMBER:	98AON87219F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	CERAMIC DIP 26, 38.1x22.61, 2.54P	PAGE 1 OF 2

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

CERAMIC DIP 26
CASE 125BA
ISSUE O


DATE 30 JUN 2014



NOTES:

- 1) FOR SINGULATION PURPOSES: DIE ON WAFER ARE STEPPED (x) 29.00 mm, (y) 19.10 mm. ASSUMING 50 MICRON KERF, SINGULATED DIE ARE 28.95 mm X 19.05 mm.
- 2) THERE IS NO INDICATOR ON DIE FOR BOND PAD 1. ORIENT THE CORNER WITH 7 BOND PADS IN THE PIN 1 CORNER OF THE PACKAGE.
- 3) WIRE LOOP HEIGHT: 0.014" +/- .003".

DOCUMENT NUMBER:	98AON87219F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	CERAMIC DIP 26, 38.1x22.61, 2.54P	PAGE 2 OF 2

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.